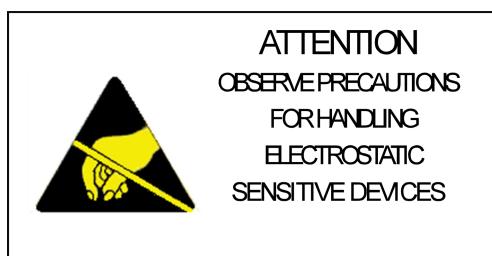


# WCN-3535UV-AE-410

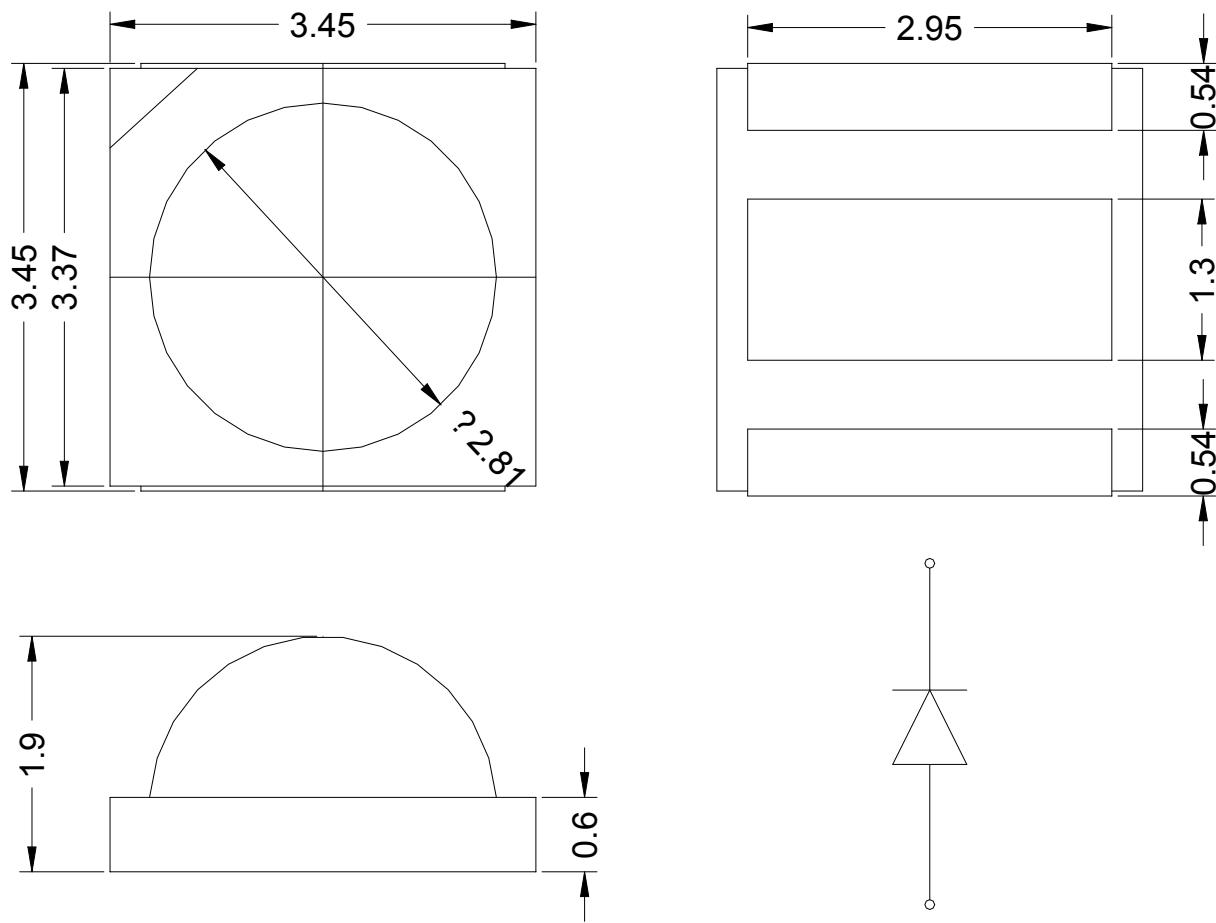
## SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
LiuGuo 2018-11-9	ZhangChun 2018-11-9		



**Description**

- ◆ Viewing angle:120 deg
- ◆ The materials of the LED dice is InGaN
- ◆ 3.45mm×3.45mm×1.9mm
- ◆ RoHS compliant lead-free soldering compatible

**Package Outline****NOTES:**

1. All dimensions units are millimeters ;
2. All dimensions tolerances are  $\pm 0.2\text{mm}$  unless otherwise noted.

**Absolute Maximum Ratings at Ta=25°C**

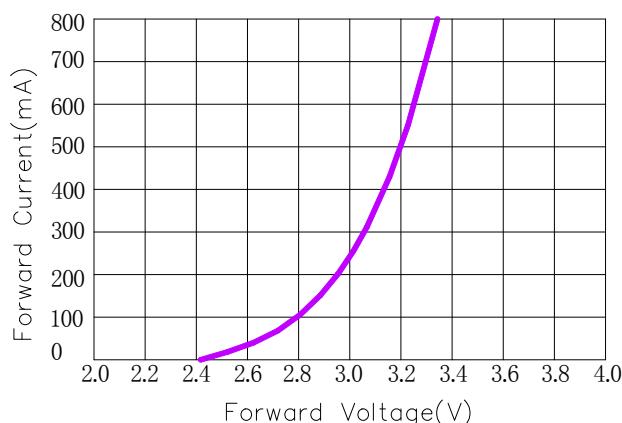
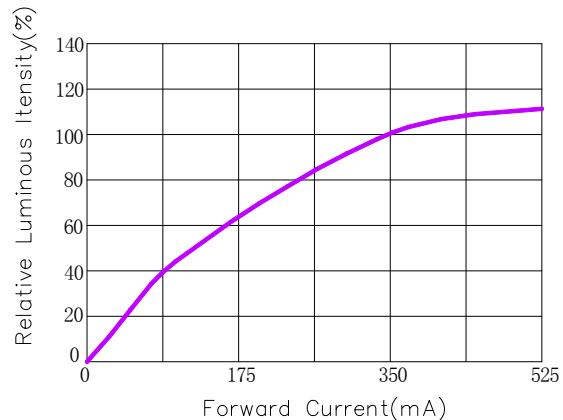
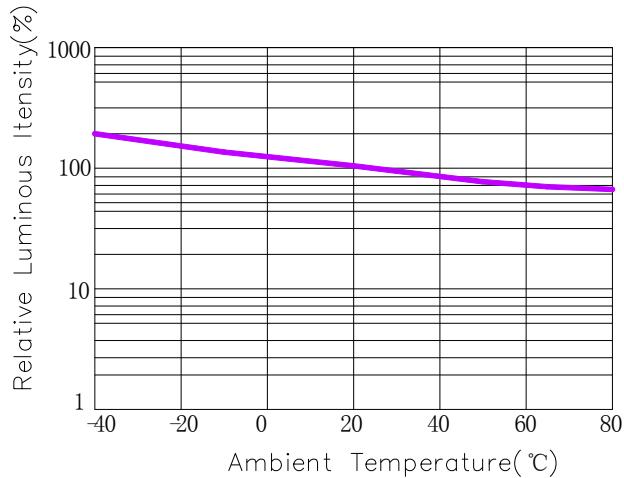
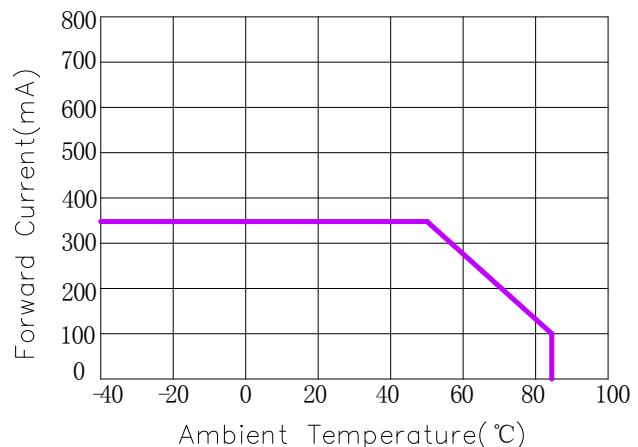
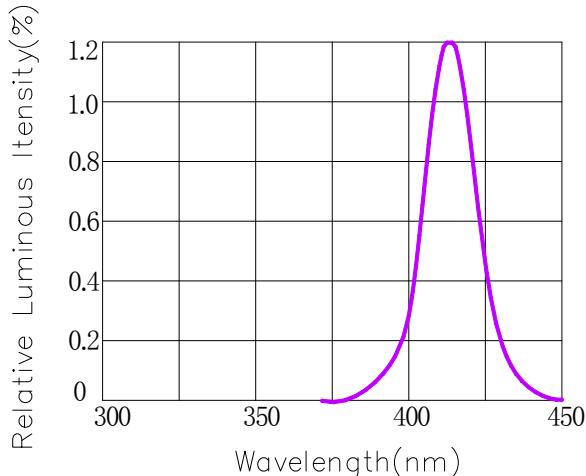
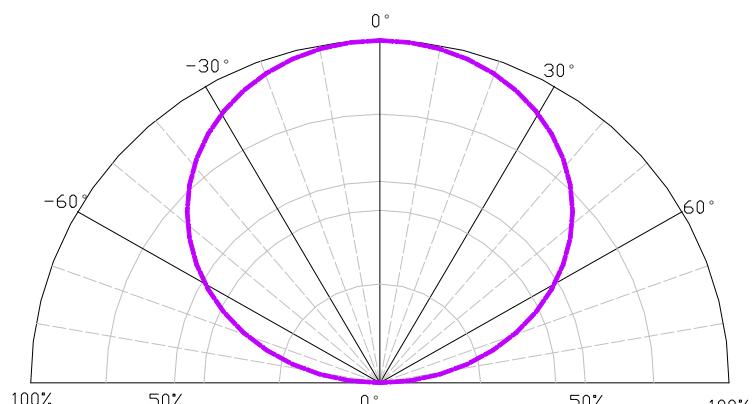
Parameter	Symbol	Rating	Units
Power Dissipation	Pd	1190	mW
Forward current	If	350	mA
Peak Forward Current	IFP	700	mA
Reverse voltage	VR	5	V
Electrostatic Discharge	ESD	1000	V
Operating temperature	Topr	-30~+85	°C
Storage temperature	Tstg	-40 ~+100	°C

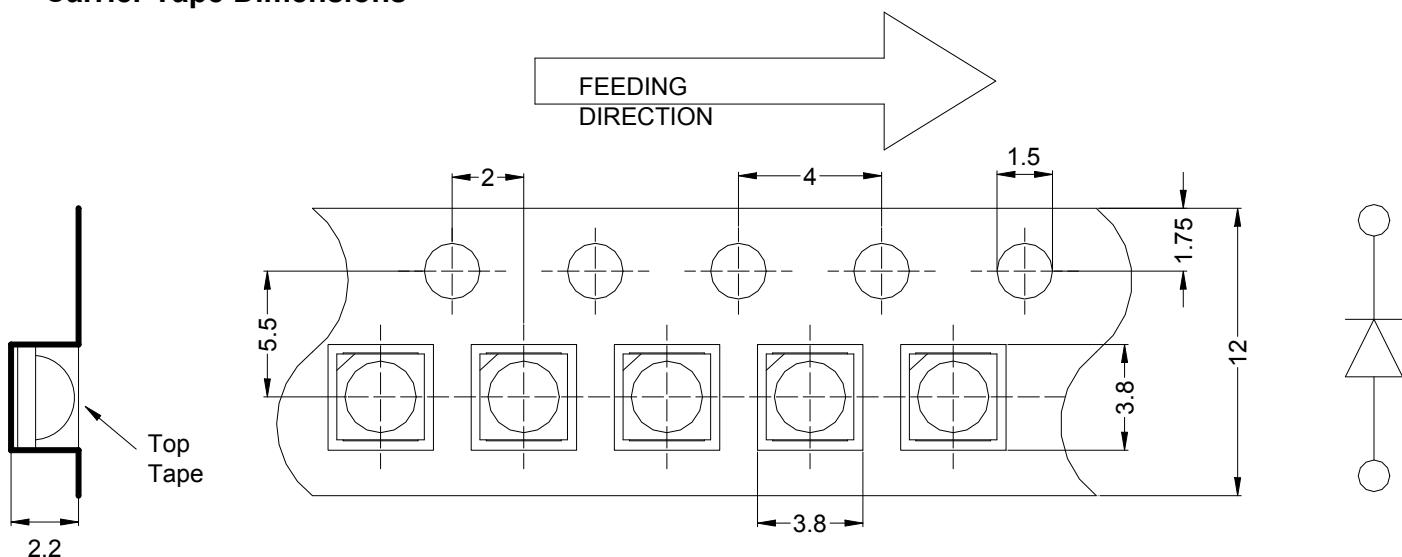
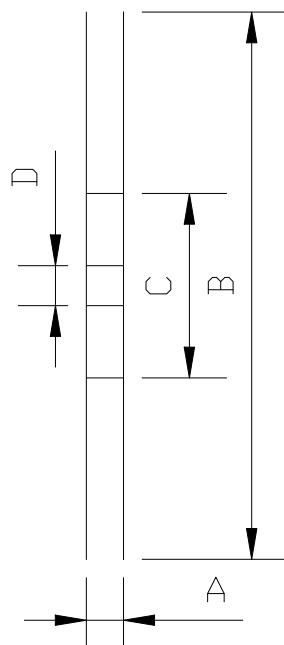
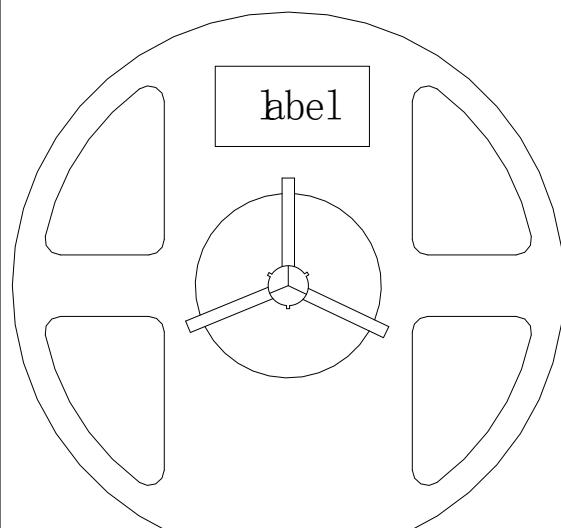
**Electrical/Optical characteristics at Ta=25°C**

Item	test condition	Symbol	Value			Unit
			Min.	Typ.	Max.	
Forward voltage	If=350mA	Vf	2.8	--	3.0	V
			3.0	--	3.2	V
			3.2	--	3.4	V
Radiant Intensity	If=350mA	IE	350	--	450	mW/sr
Peak Emission Wavelength	If=350mA	λp	410	--	415	nm
Reverse current	Vr=5V	Ir	--	--	10	μA
Viewing angle at 50% Iv	If=350mA	2θ1/2	--	120	--	Deg

**NOTE:**

- 1.1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is 0.1V.
3. the above luminous intensity measurement allowance tolerance ±10%.

**Optical characteristics curves****Forward Current VS Forward Voltage****Relative Flux VS Forward Current****Relative Flux VS Ambient Temperature****Forward Current VS Ambient Temperature****Relative Spectral Distribution****Typical Spectral Distribution**

**Packaging Specifications****■ Carrier Tape Dimensions****■ Reel Dimension**

A	16.2±0.1mm
B	178±1mm
C	60±1mm
D	21.0±0.5mm

**NOTE:**

1. The tolerances unless mentioned ±0.1mm. Unit : mm
2. 1,000 pcs/Reel.

## ■ Label Form Specification

WCN Opto Group Co., Ltd

P/N:



ROHS

QTY: PCS



IV:

WL:

VF:

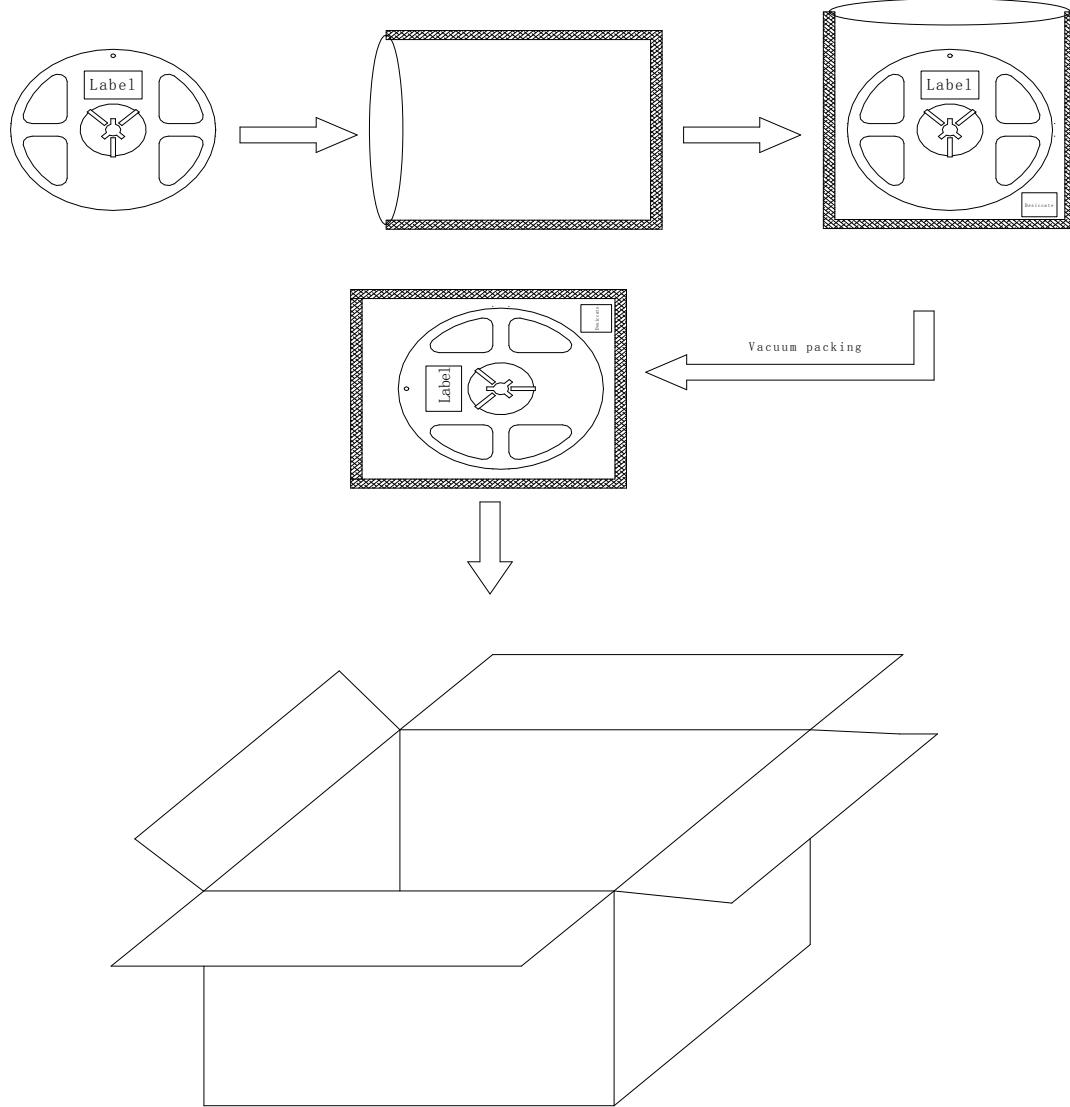
LOT NO:



MADE IN CHINA

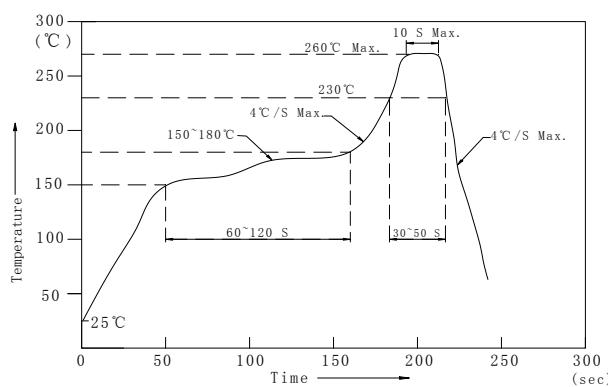
P/N	Part Number
QTY	Packing Quantity
LOT NO	Made Date
IV	Luminous intensity
WL	Peak Emission Wavelength
VF	Forward Voltage

## ■ Moisture Resistant Packing Process



**Test items and results of reliability**

Type	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Reflow	Ta=260°C max T=10s	2 times	0/22
	Temperature Cycle	-40°C 30min ↑ 100°C 30min	100 cycle	0/22
	Thermal Shock	-40°C 15min ↑ 100°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C ⇄ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	Ta=100°C	1000 hrs	0/22
	Low Temperature Storage	Ta=-40°C	1000 hrs	0/22
	Humidity Heat Storage	Ta=60°C RH=90%	1000 hrs	0/22
	Low Temperature Storage	Ta=-30°C	1000 hrs	0/22
Operation Sequence	Life Test	Ta=25°C IF=20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60°C RH=90% IF=10mA	500 hrs	0/22
	Low Temperature Life Test	Ta=-20°C IF=20mA	1000 hrs	0/22

**Reflow Profile****■ Reflow Temp/Time****Notes:**

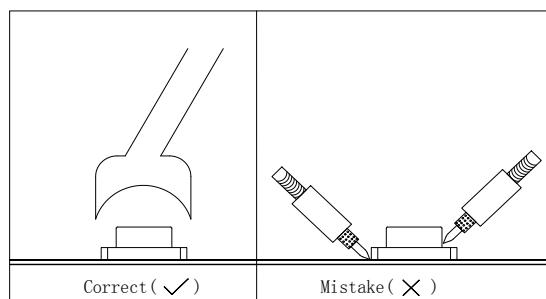
1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

**■ Soldering iron**

Basic spec is  $\leq 5\text{ sec}$  when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{ sec}$ ). Power dissipation of iron should be smaller than  $20\text{W}$ , and temperatures should be controllable .Surface temperature of the device should be under  $230^{\circ}\text{C}$  .

**■ Rework**

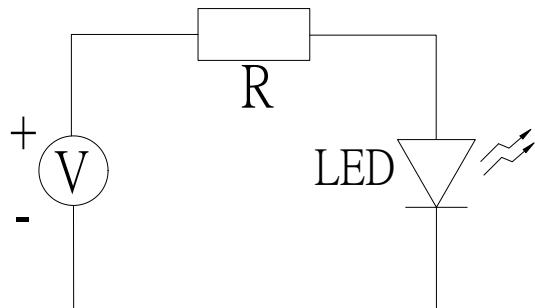
1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$ .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

## Test circuit and handling precautions

### ■ Test circuit



### ■ Handling precautions

#### 1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2. Storage

##### 2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C(41°F~86°F)

##### 2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. After the package is

Opened, the products should be used within a week or they should be keeping to stored at  $\leq 20$  R.H. with zip-lock sealed.

#### 3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as

followings:

3.1  $70\pm3^\circ\text{C}$  x(12~24hrs) and <5%RH, taped reel type

3.2  $100\pm3^\circ\text{C}$  x(45min~1hr), bulk type

3.3  $130\pm3^\circ\text{C}$  x(15~30min), bulk type